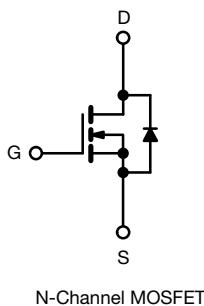
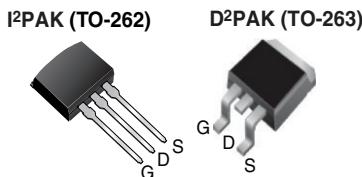


Power MOSFET



FEATURES

- Surface-mount (IRFBF20S, SiHFBF20S)
- Low-profile through-hole (IRFBF20L, SiHFBF20L)
- Available in tape and reel (IRFBF20S, SiHFBF20S)
- Dynamic dV/dt rating
- 150 °C operating temperature
- Fast switching
- Fully avalanche rated
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


RoHS*
Available

**HALOGEN
FREE**
Available

Note

* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

DESCRIPTION

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The D²PAK is a surface-mount power package capable of the accommodating die sizes up to HEX-4. It provides the highest power capability and the lowest possible on-resistance in any existing surface-mount package. The D²PAK is suitable for high current applications because of its low internal connection resistance and can dissipate up to 2.0 W in a typical surface-mount application. The through-hole version (IRFBF20L, SiHFBF20L) is available for low-profile applications.

PRODUCT SUMMARY

V_{DS} (V)	900	
$R_{DS(on)}$ (Ω)	$V_{GS} = 10$ V	8.0
Q_g max. (nC)	38	
Q_{gs} (nC)	4.7	
Q_{gd} (nC)	21	
Configuration	Single	

ORDERING INFORMATION

Package	D ² PAK (TO-263)	D ² PAK (TO-263)	D ² PAK (TO-263)	I ² PAK (TO-262)
Lead (Pb)-free and Halogen-free	SiHFBF20S-GE3	SiHFBF20STR-GE3 ^a	SiHFBF20STR-RR-GE3 ^a	SiHFBF20L-GE3
Lead (Pb)-free	IRFBF20SPbF	IRFBF20STRLPbF ^a	IRFBF20STRRRPbF ^a	IRFBF20LPbF

Note

a. See device orientation

ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-source voltage ^e	V_{DS}	900	V
Gate-source voltage ^e	V_{GS}	± 20	
Continuous drain current	I_D	1.7	A
		1.1	
Pulsed drain current ^{a, e}	I_{DM}	6.8	
Linear derating factor		0.43	W/°C
Single pulse avalanche energy ^{b, e}	E_{AS}	180	mJ
Repetitive avalanche current ^a	I_{AR}	1.7	A
Repetitive avalanche energy ^a	E_{AR}	5.4	mJ
Maximum power dissipation	P_D	54	W
		3.1	
Peak diode recovery dV/dt ^{c, e}	dV/dt	1.5	V/ns
Operating junction and storage temperature range	T_J, T_{stg}	-55 to +150	°C
Soldering recommendations (peak temperature) ^d	for 10 s	300	
Mounting torque	6-32 or M3 screw	10	N

Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- $V_{DD} = 50$ V; starting $T_J = 25$ °C, $L = 117$ mH, $R_g = 25$ Ω , $I_{AS} = 1.7$ A (see fig. 12)
- $I_{SD} \leq 1.7$ A, $dI/dt \leq 70$ A/ μ s, $V_{DD} \leq V_{DS}$, $T_J \leq 150$ °C
- 1.6 mm from case
- Uses IRFBF20, SiHFBF20 data and test conditions

THERMAL RESISTANCE RATINGS

PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient (PCB mounted, steady-state) ^a	R_{thJA}	-	40	°C/W
Maximum junction-to-case	R_{thJC}	-	2.3	

Note

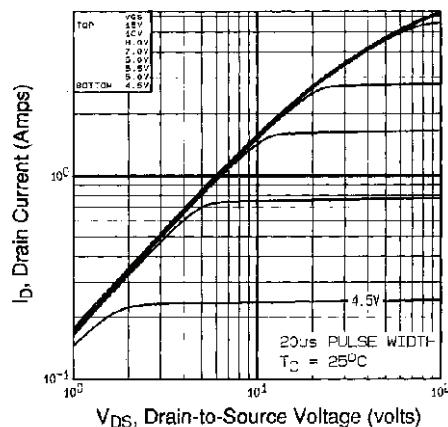
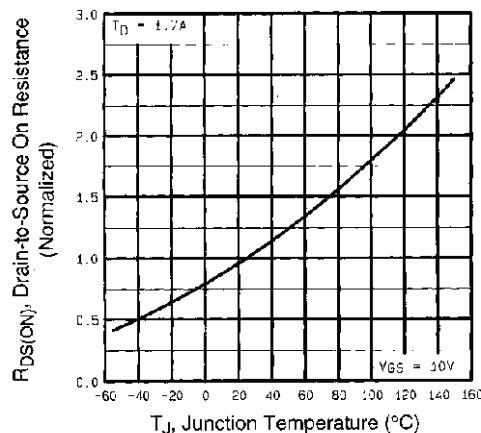
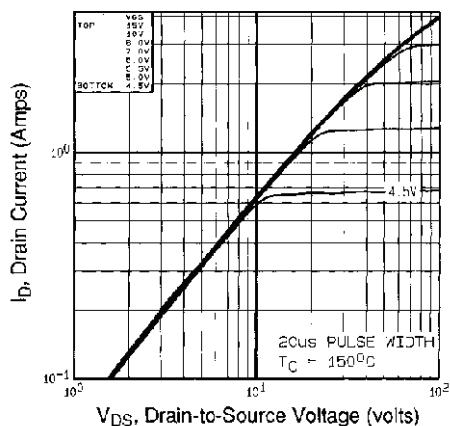
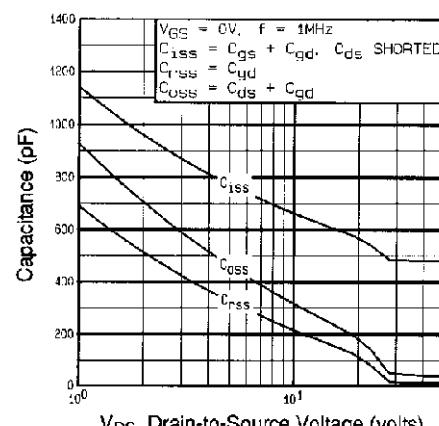
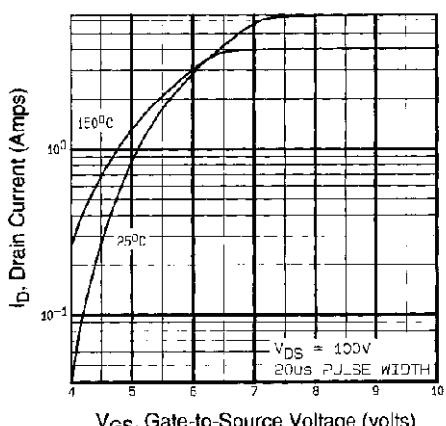
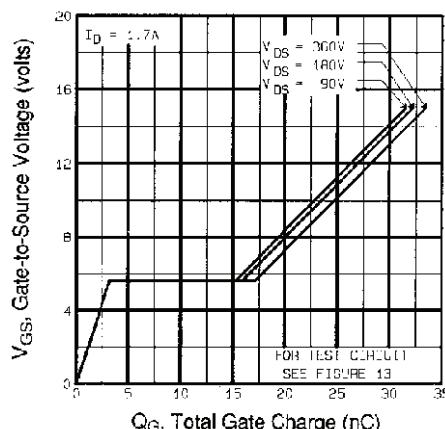
a. When mounted on 1" square PCB (FR-4 or G-10 material)

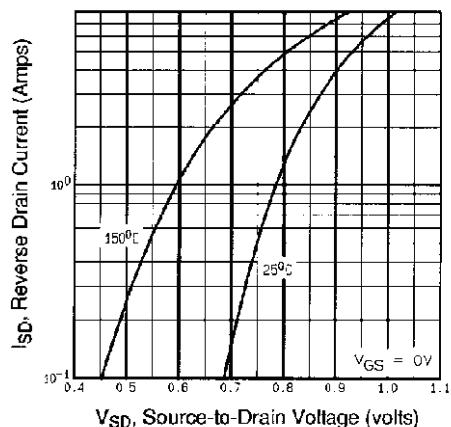
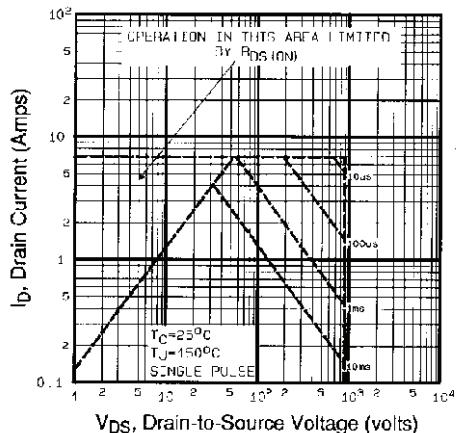
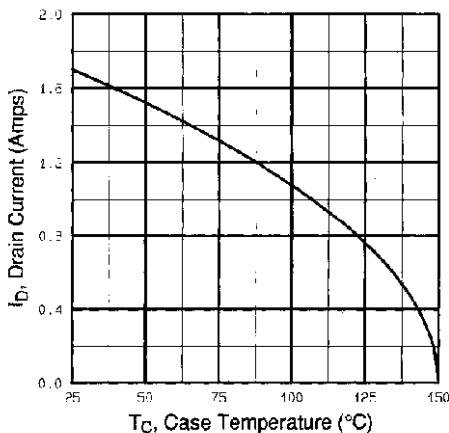
SPECIFICATIONS ($T_J = 25$ °C, unless otherwise noted)

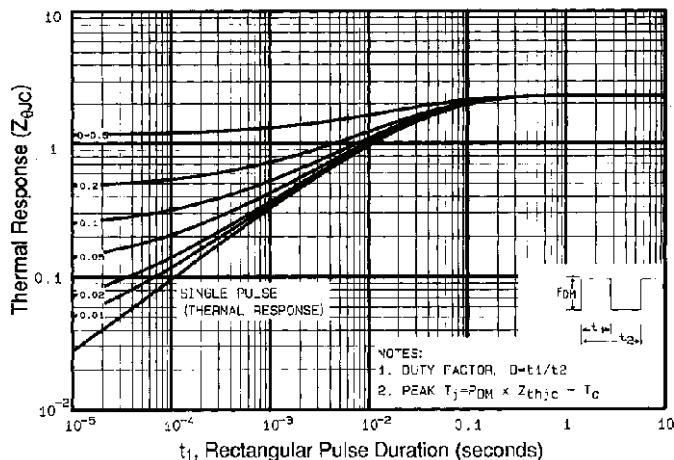
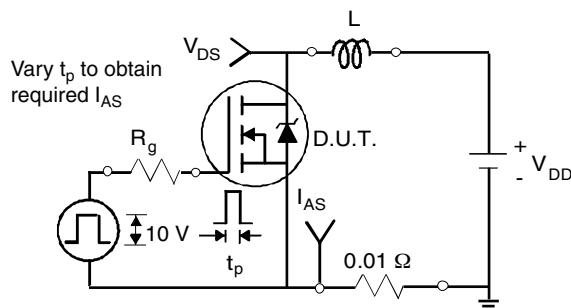
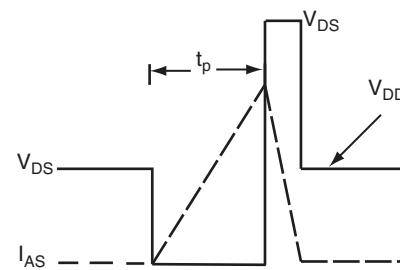
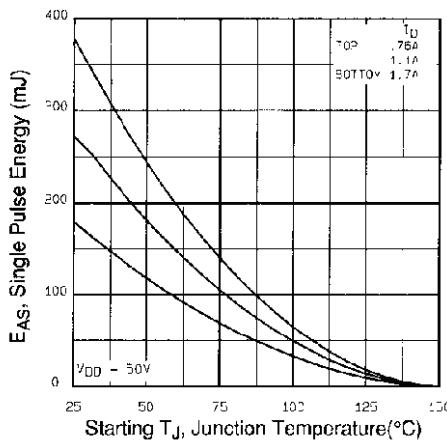
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
Static								
Drain-source breakdown voltage	V_{DS}	$V_{GS} = 0$, $I_D = 250$ µA		900	-	-	V	
V_{DS} temperature coefficient	$\Delta V_{DS}/T_J$	Reference to 25 °C, $I_D = 1$ mA		-	1.1	-	mV/°C	
Gate-source threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 250$ µA		2.0	-	4.0	V	
Gate-source leakage	I_{GSS}	$V_{GS} = \pm 20$ V		-	-	± 100	nA	
Zero gate voltage drain current	I_{DSS}	$V_{DS} = 900$ V, $V_{GS} = 0$ V		-	-	100	µA	
		$V_{DS} = 720$ V, $V_{GS} = 0$ V, $T_J = 125$ °C		-	-	500		
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS} = 10$ V	$I_D = 1.0$ A ^b	-	-	8.0	Ω	
Forward transconductance	g_{fs}	$V_{DS} = 50$ V, $I_D = 1.0$ A ^b		0.6	-	-	S	
Dynamic								
Input capacitance	C_{iss}	$V_{GS} = 0$ V, $V_{DS} = 25$ V, $f = 1.0$ MHz, see fig. 5		-	490	-	pF	
Output capacitance	C_{oss}			-	55	-		
Reverse transfer capacitance	C_{rss}			-	18	-		
Total gate charge	Q_g	$V_{GS} = 10$ V	$I_D = 1.7$ A, $V_{DS} = 360$ V, see fig. 6 and 13 ^b	-	-	38	nC	
Gate-source charge	Q_{gs}			-	-	4.7		
Gate-drain charge	Q_{gd}			-	-	21		
Turn-on delay time	$t_{d(on)}$			-	8.0	-		
Rise time	t_r	$V_{DD} = 450$ V, $I_D = 1.7$ A, $R_g = 18$ Ω, $V_{GS} = 10$ V, see fig. 10 ^b		-	21	-	ns	
Turn-off delay time	$t_{d(off)}$			-	56	-		
Fall time	t_f			-	32	-		
Gate input resistance	R_g	$f = 1$ MHz, open drain		0.6	-	3.4	Ω	
Drain-Source Body Diode Characteristics								
Continuous source-drain diode current	I_S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	1.7	A	
Pulsed diode forward current ^a	I_{SM}			-	-	6.8		
Body diode voltage	V_{SD}	$T_J = 25$ °C, $I_S = 1.7$ A, $V_{GS} = 0$ V ^b		-	-	1.5	V	
Body diode reverse recovery time	t_{rr}	$T_J = 25$ °C, $I_F = 1.7$ A, $dI/dt = 100$ A/µs ^b		-	350	530	ns	
Body diode reverse recovery charge	Q_{rr}			-	0.85	1.3	µC	
Forward turn-on time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D)						

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
b. Pulse width ≤ 300 µs; duty cycle ≤ 2 %
c. Uses IRFBF20/SiHFBF20 data and test conditions

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Fig. 1 - Typical Output Characteristics

Fig. 4 - Normalized On-Resistance vs. Temperature

Fig. 2 - Typical Output Characteristics

Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

Fig. 3 - Typical Transfer Characteristics

Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Fig. 7 - Typical Source-Drain Diode Forward Voltage

Fig. 8 - Maximum Safe Operating Area

Fig. 9 - Maximum Drain Current vs. Case Temperature

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Fig. 12 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

Fig. 12a - Unclamped Inductive Test Circuit

Fig. 12b - Unclamped Inductive Waveforms

Fig. 12c - Maximum Avalanche Energy vs. Drain Current

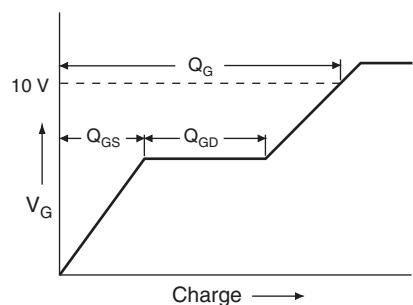


Fig. 13a - Basic Gate Charge Waveform

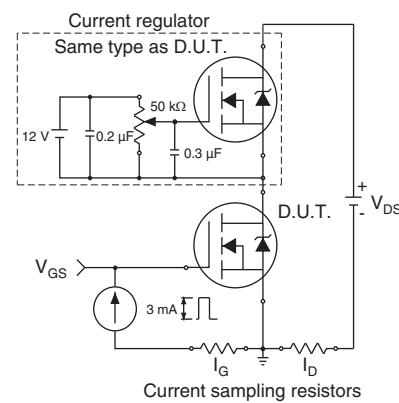


Fig. 13b - Gate Charge Test Circuit

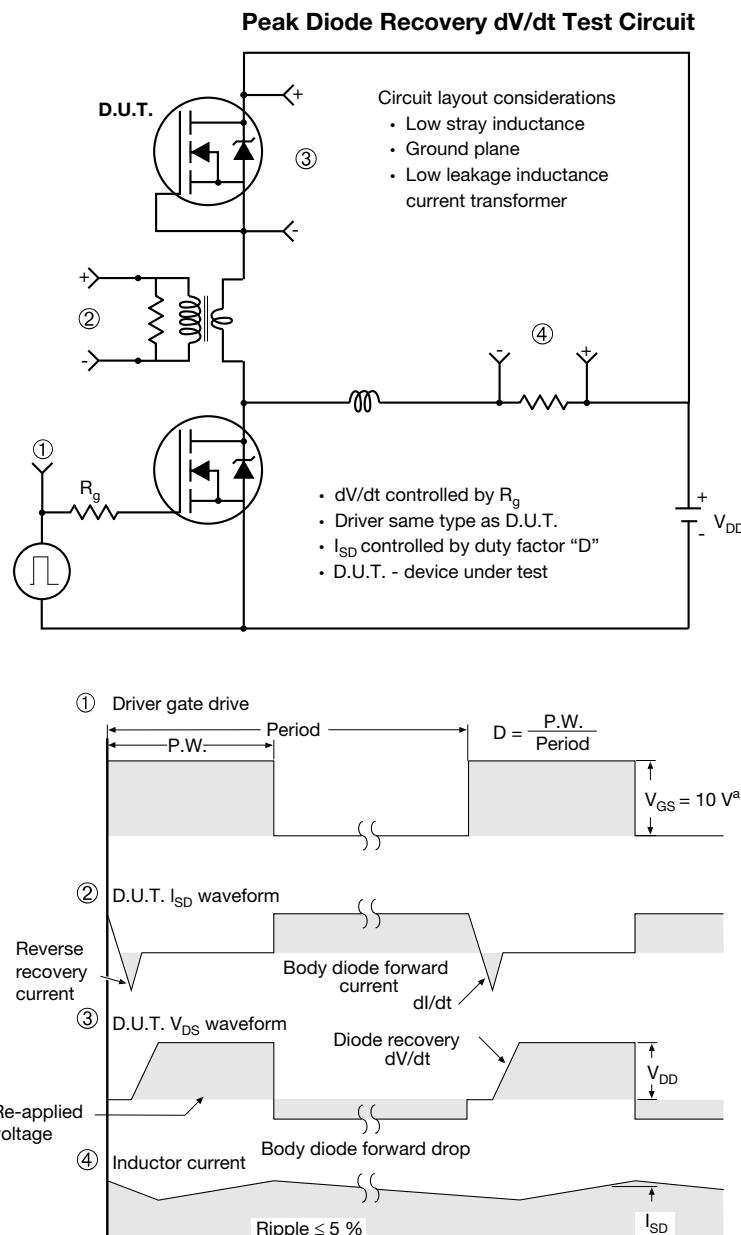
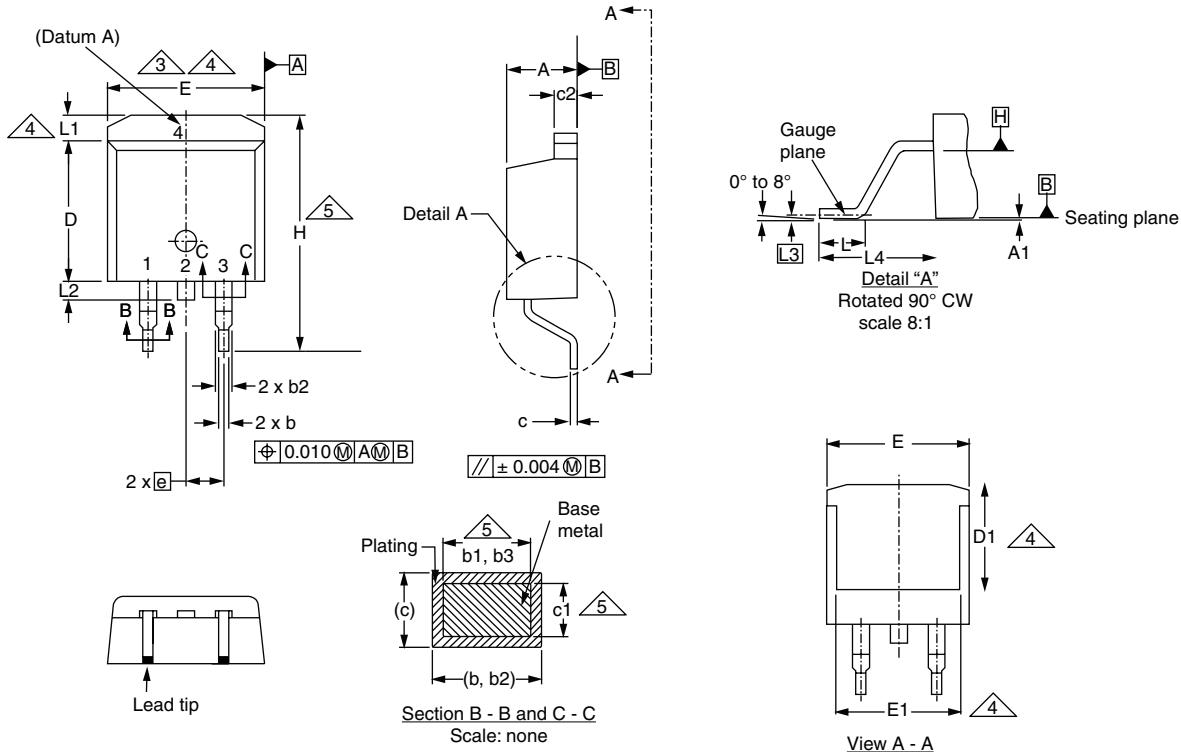


Fig. 14 - For N-Channel

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TO-263AB (HIGH VOLTAGE)



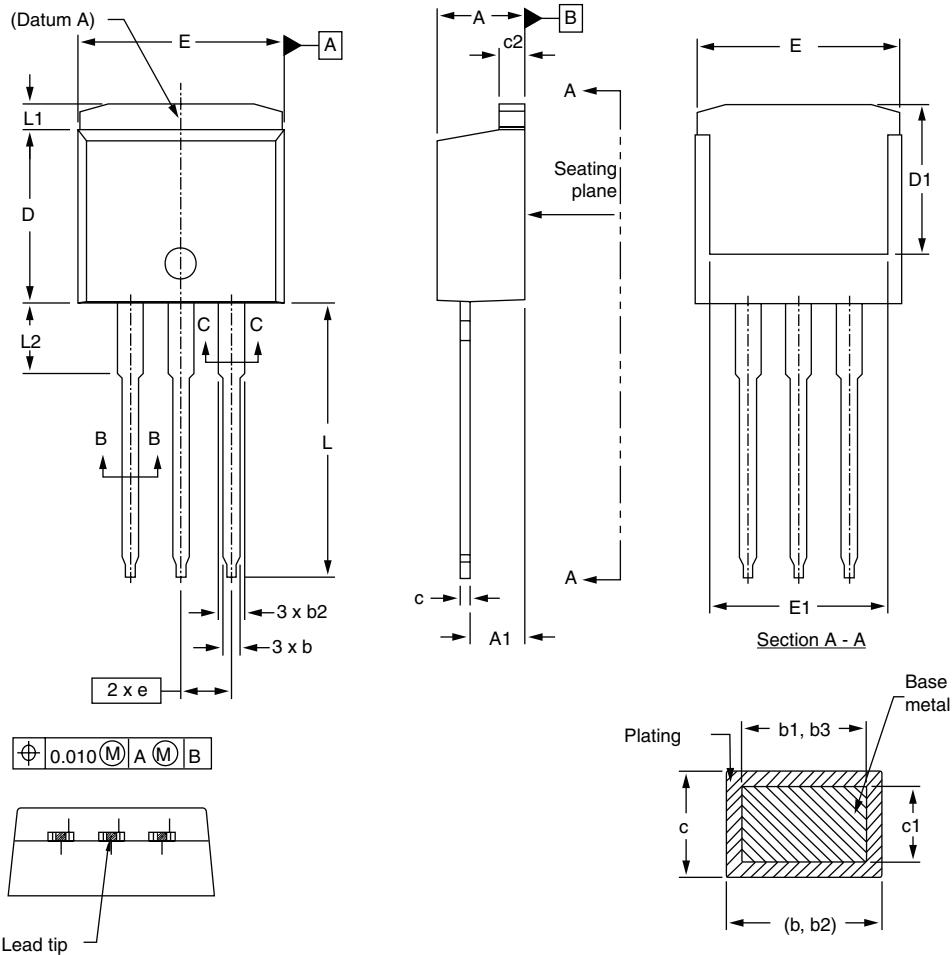
	MILLIMETERS		INCHES	
DIM.	MIN.	MAX.	MIN.	MAX.
A	4.06	4.83	0.160	0.190
A1	0.00	0.25	0.000	0.010
b	0.51	0.99	0.020	0.039
b1	0.51	0.89	0.020	0.035
b2	1.14	1.78	0.045	0.070
b3	1.14	1.73	0.045	0.068
c	0.38	0.74	0.015	0.029
c1	0.38	0.58	0.015	0.023
c2	1.14	1.65	0.045	0.065
D	8.38	9.65	0.330	0.380

	MILLIMETERS		INCHES	
DIM.	MIN.	MAX.	MIN.	MAX.
D1	6.86	-	0.270	-
E	9.65	10.67	0.380	0.420
E1	6.22	-	0.245	-
e	2.54 BSC		0.100 BSC	
H	14.61	15.88	0.575	0.625
L	1.78	2.79	0.070	0.110
L1	-	1.65	-	0.066
L2	-	1.78	-	0.070
L3	0.25 BSC		0.010 BSC	
L4	4.78	5.28	0.188	0.208

Notes

1. Dimensioning and tolerancing per ASME Y14.5M-1994.
2. Dimensions are shown in millimeters (inches).
3. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body at datum A.
4. Thermal PAD contour optional within dimension E, L1, D1 and E1.
5. Dimension b1 and c1 apply to base metal only.
6. Datum A and B to be determined at datum plane H.
7. Outline conforms to JEDEC outline to TO-263AB.

I²PAK (TO-262) (HIGH VOLTAGE)



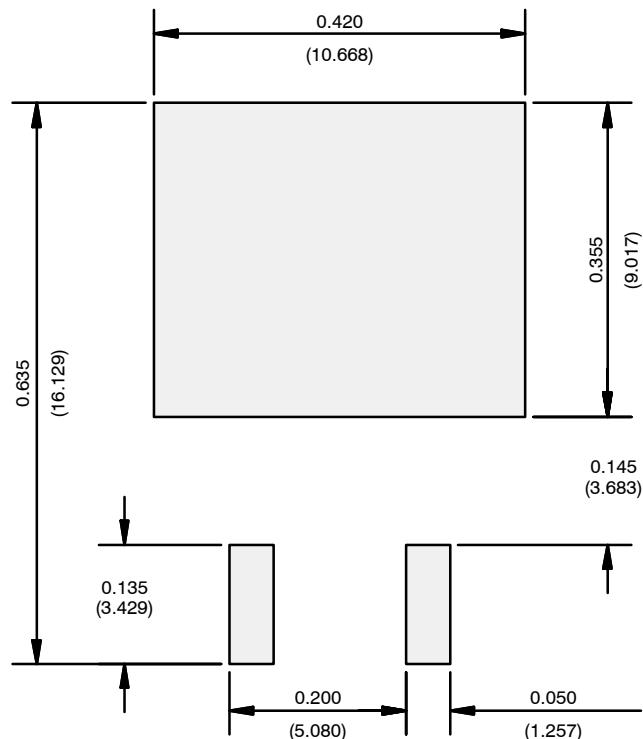
DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	4.06	4.83	0.160	0.190
A1	2.03	3.02	0.080	0.119
b	0.51	0.99	0.020	0.039
b1	0.51	0.89	0.020	0.035
b2	1.14	1.78	0.045	0.070
b3	1.14	1.73	0.045	0.068
c	0.38	0.74	0.015	0.029
c1	0.38	0.58	0.015	0.023
c2	1.14	1.65	0.045	0.065

ECN: S-82442-Rev. A, 27-Oct-08
DWG: 5977

DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
D	8.38	9.65	0.330	0.380
D1	6.86	-	0.270	-
E	9.65	10.67	0.380	0.420
E1	6.22	-	0.245	-
e	2.54 BSC		0.100 BSC	
L	13.46	14.10	0.530	0.555
L1	-	1.65	-	0.065
L2	3.56	3.71	0.140	0.146

Notes

- Dimensioning and tolerancing per ASME Y14.5M-1994.
- Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm per side. These dimensions are measured at the outmost extremes of the plastic body.
- Thermal pad contour optional within dimension E, L1, D1, and E1.
- Dimension b1 and c1 apply to base metal only.

RECOMMENDED MINIMUM PADS FOR D²PAK: 3-Lead

Recommended Minimum Pads
Dimensions in Inches/(mm)

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